

HTF-VT-VTC Series Surface Mount Quartz Crystal Units for Low Frequencies (New)



FEATURES

- IR reflowable tubular type crystal with lead bent in tape/reel.
- Suitable for automatic and high, density surface mounting.
- Excellent shock and heat resistance.

APPLICATIONS

- Radio Communication Equipment, Pagers, Cellular Telephones, Camcorders, Portable Applications, Clock Source for Micro-Computers

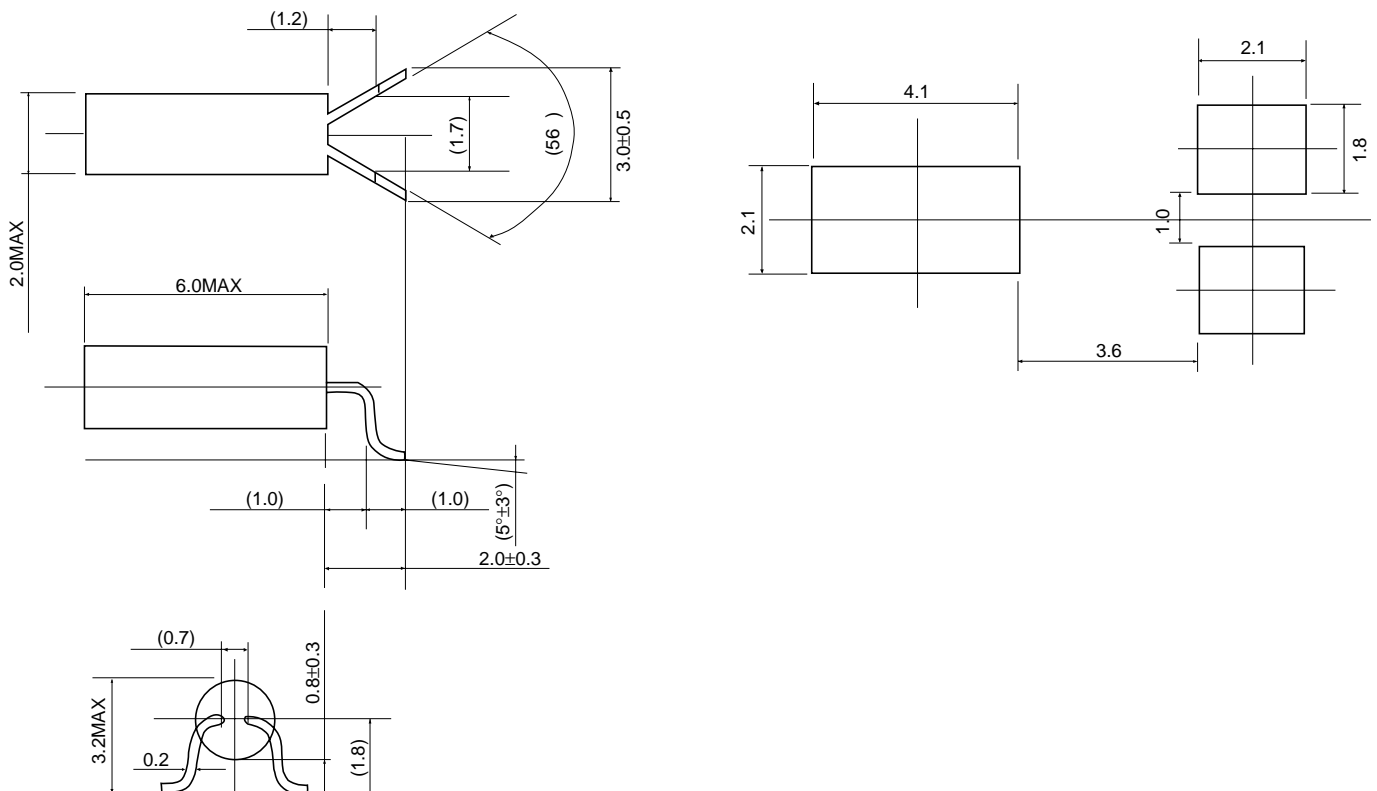
STANDARD SPECIFICATIONS

Conditions without notice (Temperature: +25°C ±2°C)

Item	Symbol	HTF-VT/VTC		Conditions
Nominal Frequency	f_0	32.768kHz	32.0kHz~153.6kHz	
Frequency Tolerance	$\Delta f/f_0$	±20ppm, ±50ppm, ±100ppm		
Turnover Temperature	T_p	±25°C±5°C	±25°C±8°C	
Temperature Coefficient	K	$(-3.5\pm 0.8)\times 10^{-8}/^{\circ}\text{C}^2$		
Load Capacitance	C_L	6.0 to 12.5pF		
Equivalent Series Resistance	R_1	50kΩ max.		
Maximum excitation level	D_{max}	1.0μW		
Drive Level	DL	0.1μW		
Shunt Capacitance	C_0	0.8pF typ.	0.5pF typ.~0.9pF typ.	
Aging	$\Delta f/f_0$	±3ppm max.	±5ppm max.	+25°C±3°C, First Year
Operating Temperature Range	T_{ope}	-20°C to +70°C		
Storage Temperature Range	T_{sto}	-40°C to +80°C		
Solderability	T_{sol}	230°C max., 20sec.max.		IR Reflow

DIMENSIONS

(For details, please refer to individual specifications)



Quartz Crystal Unit Handling Precautions

1. Mounting Precautions

1.1 Lead Type Crystal Units

1.1.1 Structure

Tubular crystal units (VT, VTC, MGQ, and MAT) are hermetically sealed using glass (see Figures 1 and 2).

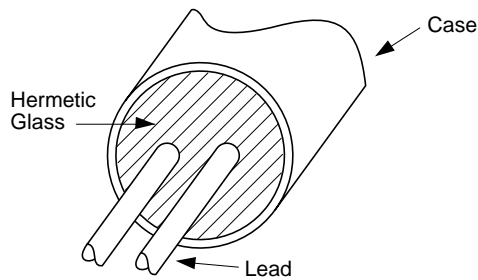


Figure 1

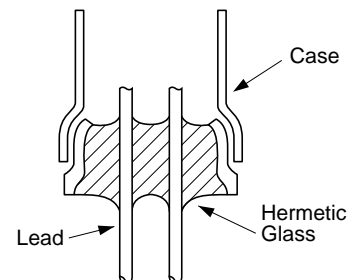


Figure 2

1.1.2 Unbending the lead

- (1) **DO NOT** pull the lead excessively if unbending a lead or removing a crystal unit. The excessive force may crack the glass and reduce the degree of vacuum. This may eventually result in deterioration of the characteristics and may also break the crystal chip (see Figure 3).
- (2) Unbend the lead by pressing on the bent part from both the upper and lower sides with fixing the bottom of lead tightly. (see Figure 4).

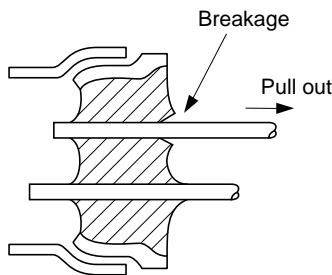


Figure 3

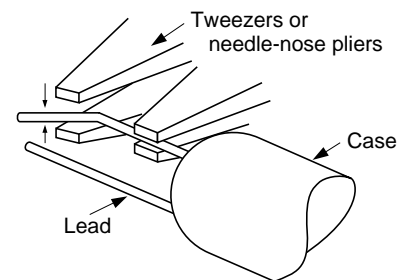


Figure 4

1.1.3 Bending the lead

- (1) Bend the lead so that the lead remains straight for more than 0.5mm from the case when soldering after bending a lead. If not, the glass may be cracked (see Figures 5 and 6).
- (2) Always leave a length greater than the case diameter when bending a lead after soldering (see Figure 7).

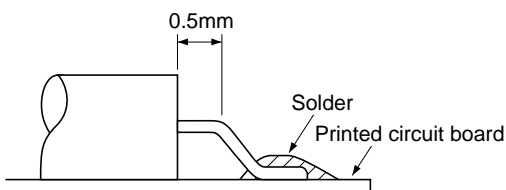


Figure 5

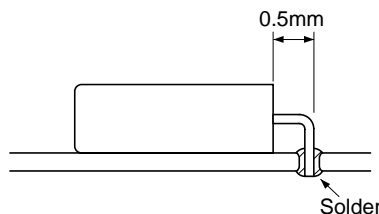


Figure 6

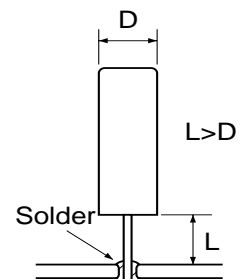


Figure 7

Soldering directly to the case will reduce the degree of vacuum and may result in deterioration of the characteristics and may break the crystal chip.

Make the length from the case to the printed circuit board (L) longer than the case diameter (D) so that the lead wire will not be pulled if the crystal unit falls over.

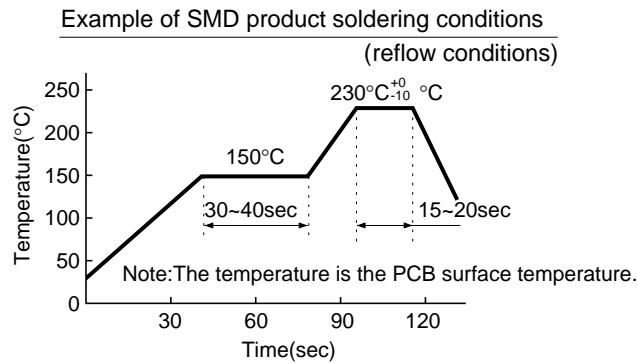
1.1.4 Soldering

Heat the lead wire at a temperature of less than 280°C for 5 seconds or less, when mounting or removing a crystal unit. A long period time of heating may result in deterioration of the characteristics and may break the crystal unit.

1.2. SMD Type Quartz Crystal Units

1.2.1 Soldering

- (1) For mounting, it is recommended to solder at less than 230°C for 20 seconds or less. An example of the infrared ray reflow temperature profile is shown as follows (see Figure 8).



2. Cleaning

- (1) Since low or intermediate frequency crystal units (VT, VTC, and MGQ) or oscillators use a small, thin crystal chip and the frequency approximates the frequency of an ultrasonic cleaner, the crystal chip may break easily. Therefore, DO NOT perform ultrasonic cleaning.
- (2) Other crystal units may also break depending upon the ultrasonic cleaning condition. Please check the ultrasonic cleaning condition.

3. Mechanical Shock

- (1) The quartz crystal units are designed to withstand a drop from a height of 75 cm onto a hard wooden board at least three times. However, the crystal chip may break if dropped, depending upon the how they are dropped. Ensure that the crystal unit functions normally, if the crystal units have been dropped or subjected to an excessive mechanical shock.
- (2) Unlike chip parts for resistors, and capacitors, the crystal unit has a crystal chip which is hermetically sealed inside. Before using the crystal units, check the influence of shock caused during automatic mounting.

Packing

The following is the standard packing. In the case of a small quantity of products (less than 1 lot), this packing may differ.

1. Lead type products

One hundred to five hundred units are packed in a vinyl bag. Twenty to forty bags are packed in a box and shipped.

Product name	Quantity per lot	Quantity per bag	Quantity per box
VT Series	10,000 pcs.	500 pcs.	20 bags
VTC Series	10,000 pcs.	500 pcs.	20 bags
MAT Series	4,000 pcs.	100 pcs.	40 bags

The following products are individually packed in a partitioned styrofoam package (150 pcs.). Several packages are bound and packed in a delivery container to ship.

Product name	Quantity per lot	Quantity per package	Quantity per container
MGQ Series	600 pcs.	150 pcs.	4 packages
MGXO Series	100 pcs.	Stuck into a conductive mat and packed in a box.	

2. SMD products

After being taped, the products are rolled onto a reel. The reels are packed in a box.

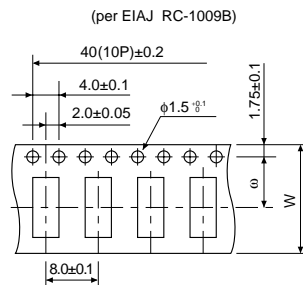
Product name	SP-T1	SP-T2	SP-T3	HTF-VT/VTC
Quantity per reel	2,000 pcs.	3,000 pcs.	3,000 pcs.	3,000 pcs.

Note: Specifications may differ when shipped in small quantities.

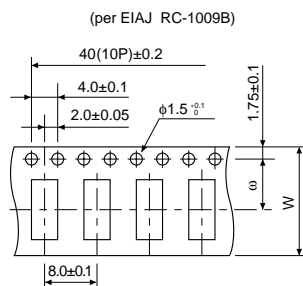
Tape and reel configuration

Emboss taping configuration

SP-T1/T2/T3

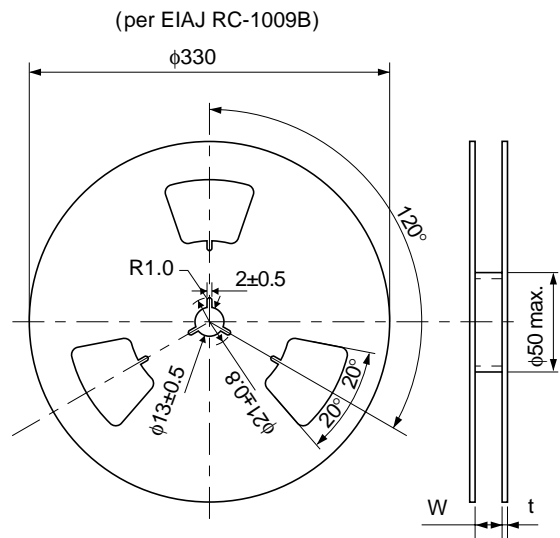


HTF-VT-VTC



	SP-T1/T2/T3,HTF-VT/VTC
ω	7.5
W	16.0

Reel configuration



	SP-T1/T2/T3,HTF-VT/VTC
W	16.4
t	2.0

UNIT: mm